

# Surface-Mount Devices | 1206 Size

## **SRF1206 Series**

### **PTC Resettable Fuses**

### **Features**

- Resettable over current and over temperature protection
- Small size of 1206
- Fast time-to-trip
- Small footprint
- RoHS complaint
- Low resistance







# **Applications**

- Computer
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband
- Mobile phones
- Battery
- Industrial controls



### **Electrical Characteristics**

	$I_{H}$	$I_{T}$	$V_{\text{max}}$	$I_{max}$	Time	to Trip	$Pd_{typ}$	$R_{min}$	$R1_{\text{max}}$
Part Number	(A)	(A)	(V)	(A)	(A)	(Sec.)	(W)	$(\Omega)$	$(\Omega)$
SRF1206P150/16	1.50	3.00	16	50	8.0	0.30	0.8	0.025	0.130

 $l_{\text{H}}\!=$  Hold current: maximum current at which the device will not trip at 25  $^{\circ}$  still air reflow soldering of 260  $^{\circ}$  for 20 sec.

Value specified is determined by using the PWB with 0.030" \*1.5oz copper traces. Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

# Thermal Derating Chart Hold Current (A)

Part Number				Ambien	t Operatino	g Temperat	ure		
rait Number	<b>-40</b> °C	<b>-20</b> °C	<b>0</b> °C	<b>25</b> °C	<b>40</b> °C	<b>50</b> °C	<b>60</b> °C	<b>70</b> °C	<b>85</b> °C
SRF1206P150/16	2.18	1.94	1.72	1.50	1.28	1.17	1.06	0.96	0.77

 $l_T$  = Trip current: minimum current at which the device will always trip at 25  $^{\circ}$  Still air reflow soldering of 260  $^{\circ}$  for 20 sec.

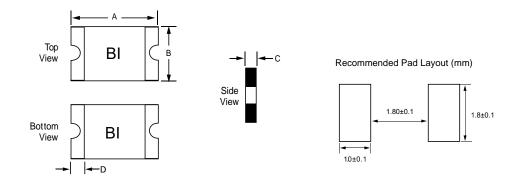
 $V_{max}$  = Maximum continuous voltage device can withstand without damage at rated current  $I_{max}$  = Maximum fault current device can withstand without damage at rated voltage.  $T_{trip}$  = Maximum time to trip(s) at assigned current reflow soldering of 260  $^\circ$  for 20 sec.

 $T_{trip}$  = Maximum time to trip(s) at assigned current reflow soldering of 260  $^{\rm C}$  for 20 sec.  $P_{dyp}$  = Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.

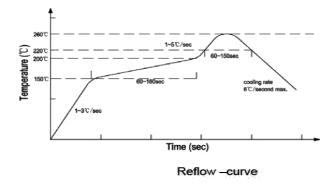
R1<sub>max</sub> = Maximum resistance of device at 25 °C measured one hour after reflow soldering of 260 °C for 20 sec.

### **Dimensions**



D. (N. ol.)	Α		В		С		D
Part Number	Min	Max	Min	Max	Min	Max	Min
SRF1206P150/16	3.00	3.60	1.50	1.90	0.50	1.60	0.10

### **Solder Reflow Recommendation**



Recommended reflow methods:IR,hot air oven ,nitrogen oven

Devices can be cleaned using standard industry methods and solvents.

#### NOTE:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

## **Packaging Options**

Part Number	Quantity
SRF1206P150/16	3,500pcs

Reel packaging per EIA-481-1 standard

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